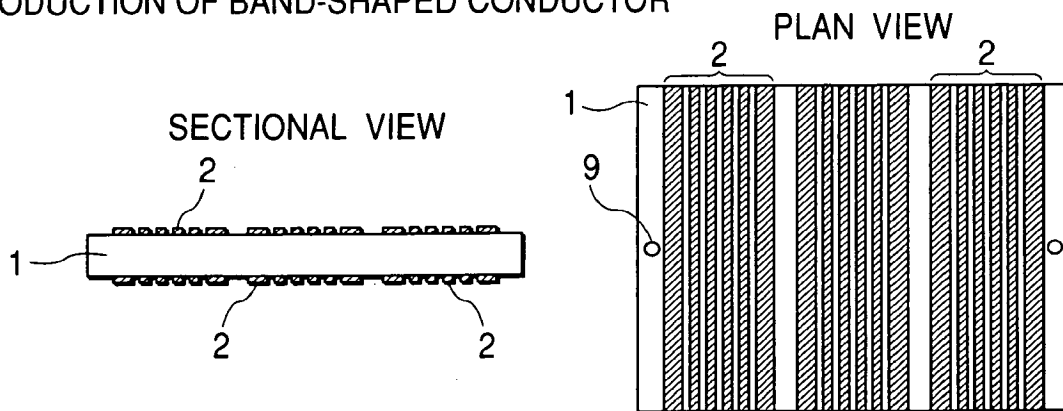




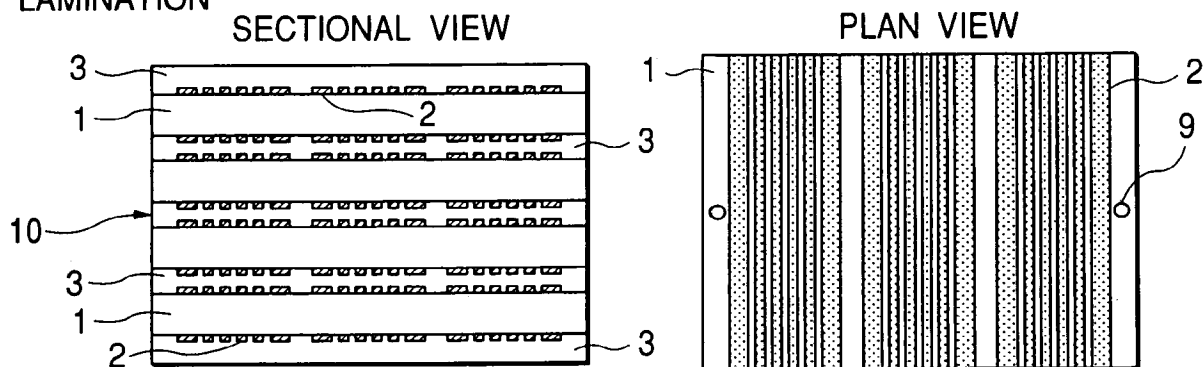
**FIG. 1A**

PRODUCTION OF BAND-SHAPED CONDUCTOR



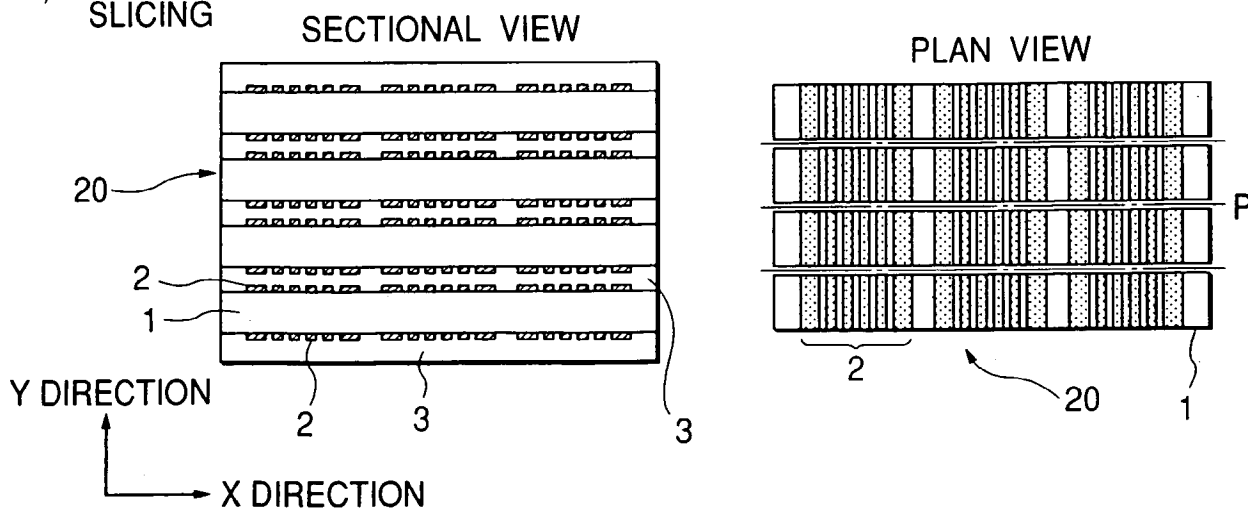
**FIG. 1B**

LAMINATION



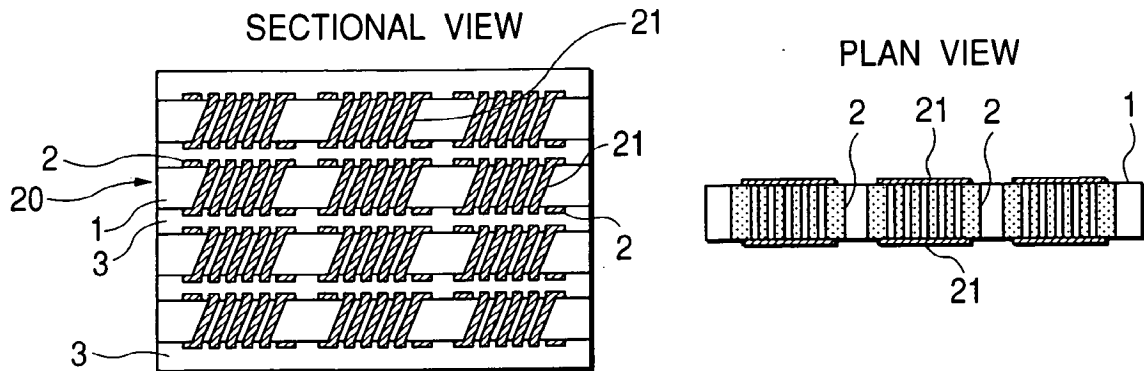
**FIG. 1C**

SLICING



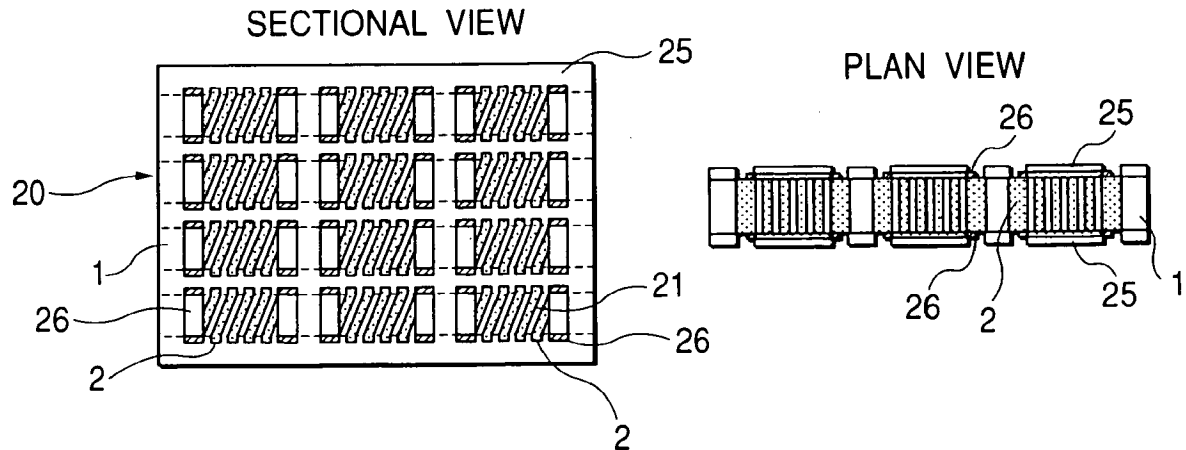
**FIG. 2A**

FORMATION OF BRIDGING CONDUCTOR



**FIG. 2B**

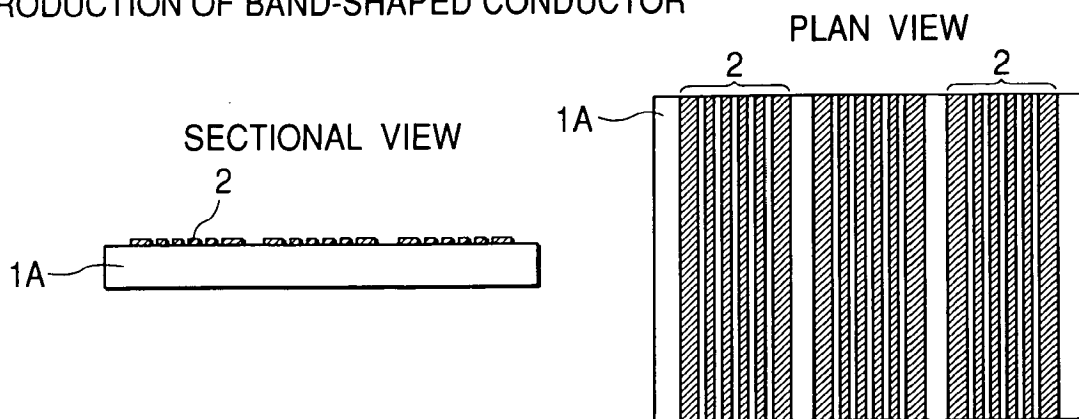
FORMATION OF PROTECTIVE LAYER





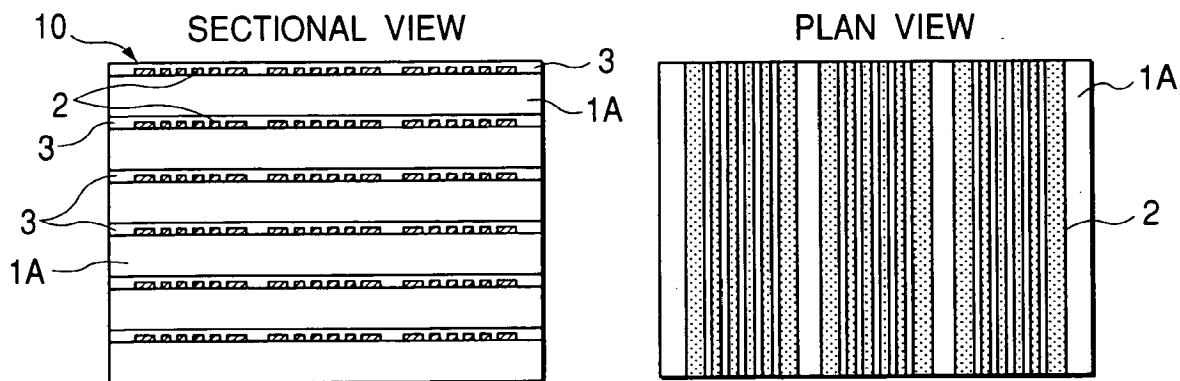
**FIG. 3A**

PRODUCTION OF BAND-SHAPED CONDUCTOR



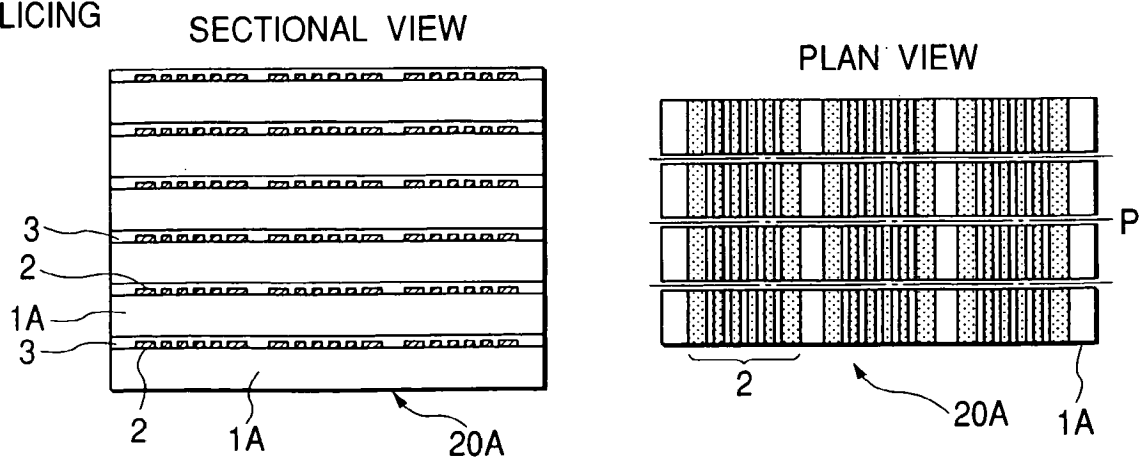
**FIG. 3B**

LAMINATION



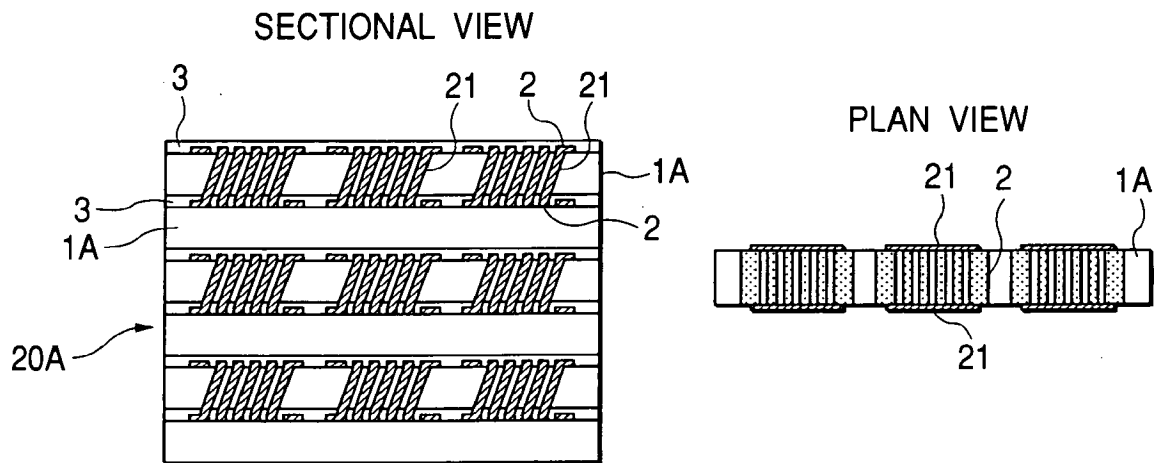
**FIG. 3C**

SLICING



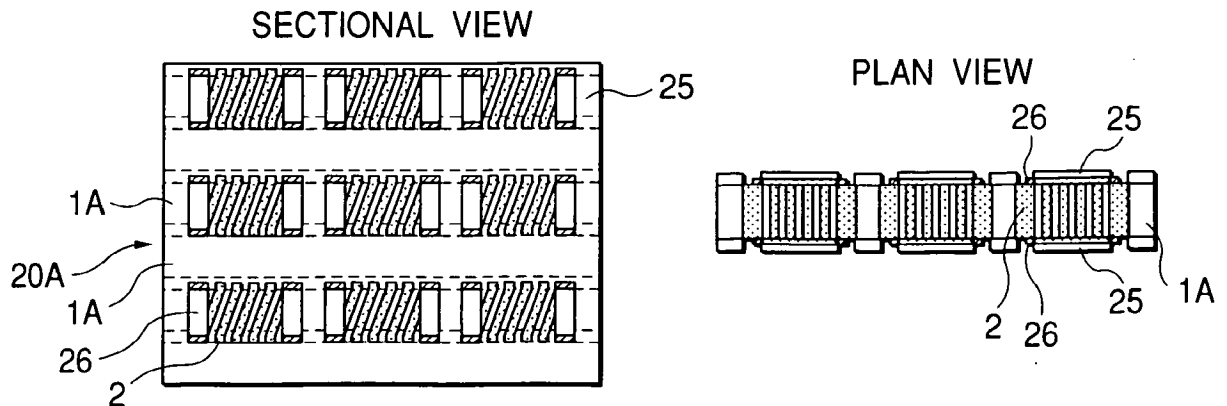
**FIG. 4A**

FORMATION OF BRIDGING CONDUCTOR



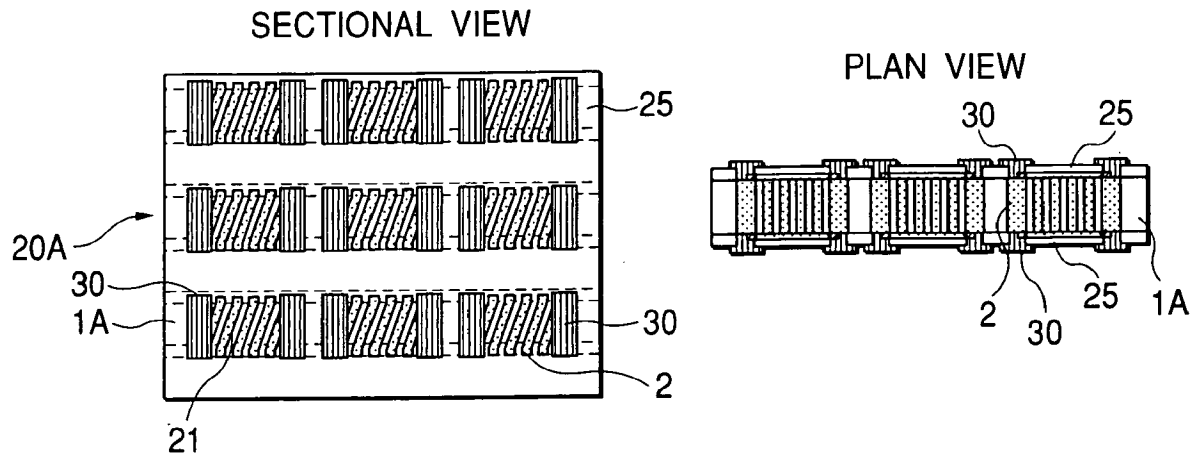
**FIG. 4B**

FORMATION OF PROTECTIVE LAYER



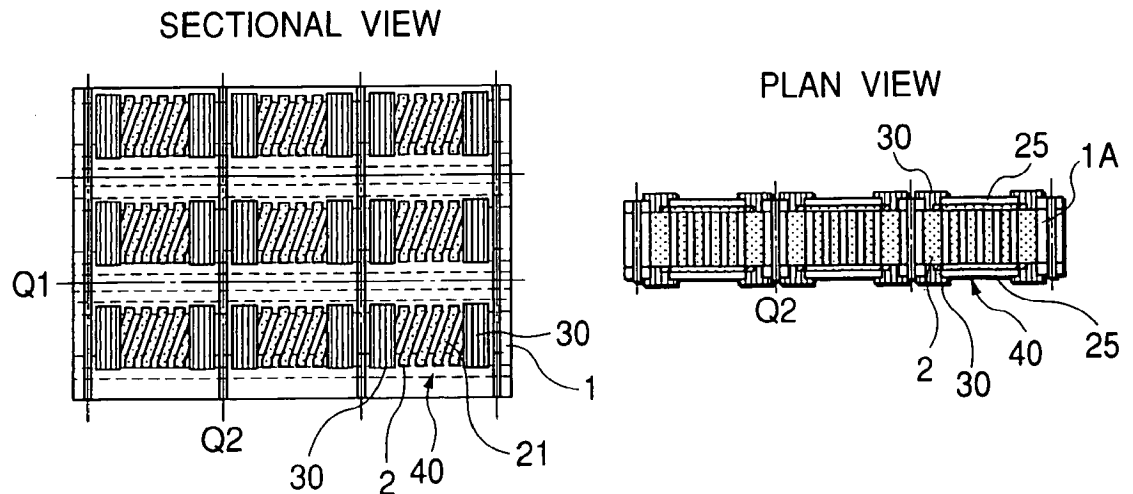
**FIG. 4C**

FORMATION OF TERMINAL ELECTRODE



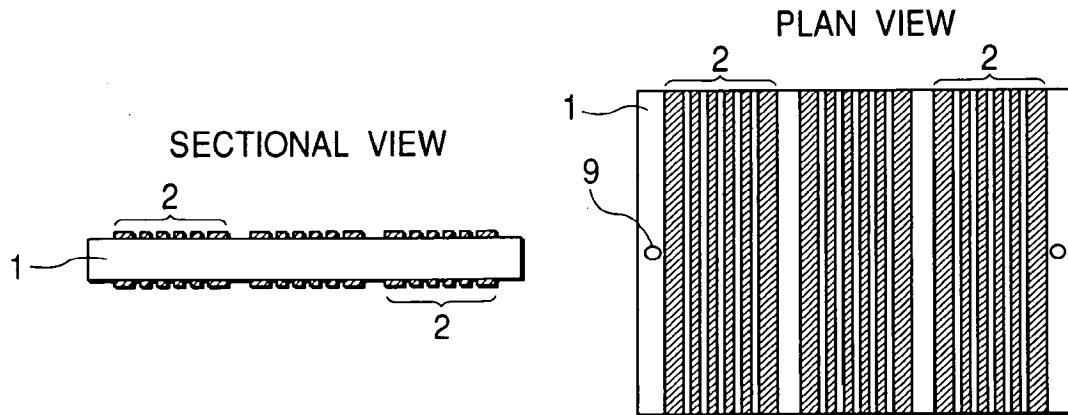
**FIG. 4D**

SEPARATION INTO CHIPS



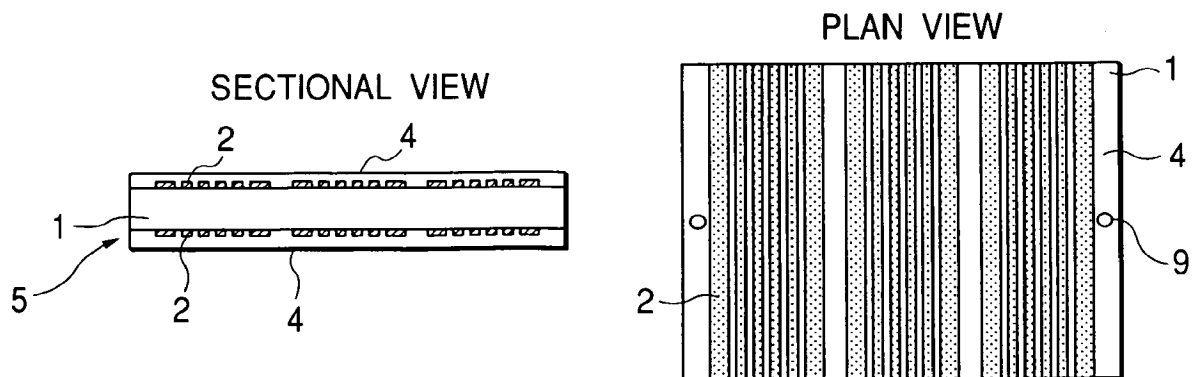
**FIG. 5A**

PRODUCTION OF BAND-SHAPED CONDUCTOR



**FIG. 5B**

FIRST LAMINATION

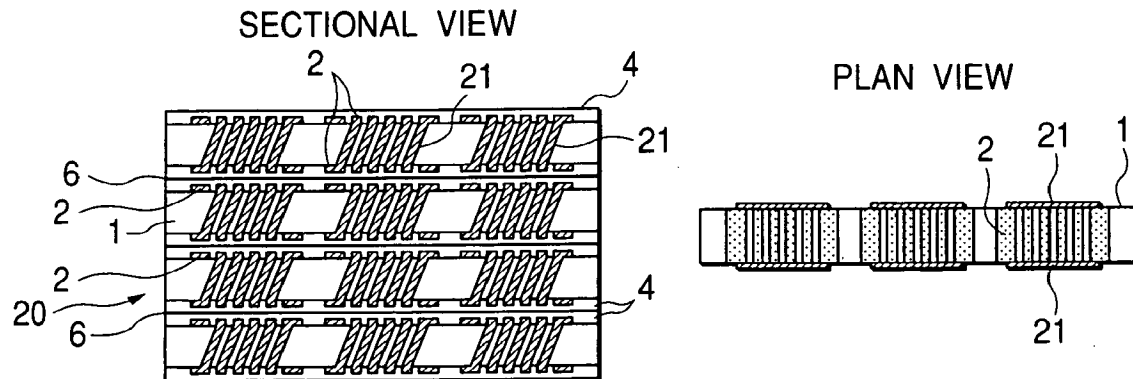






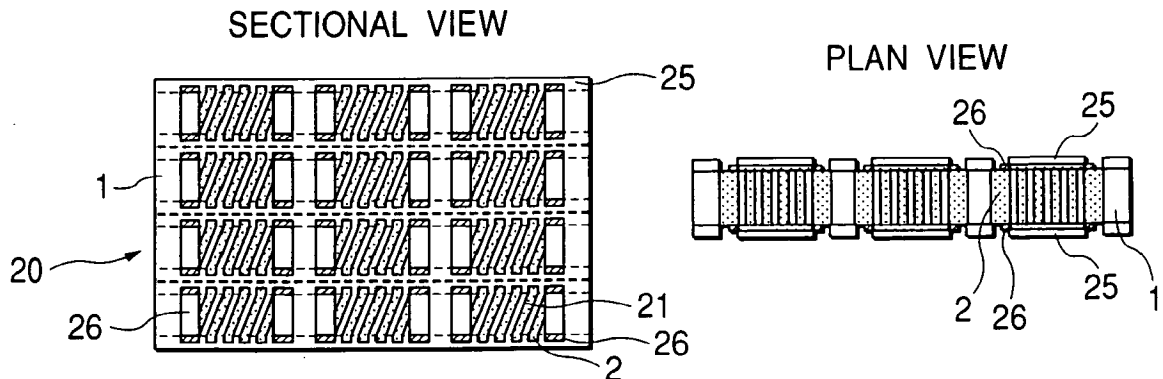
**FIG. 6A**

FORMATION OF BRIDGING CONDUCTOR



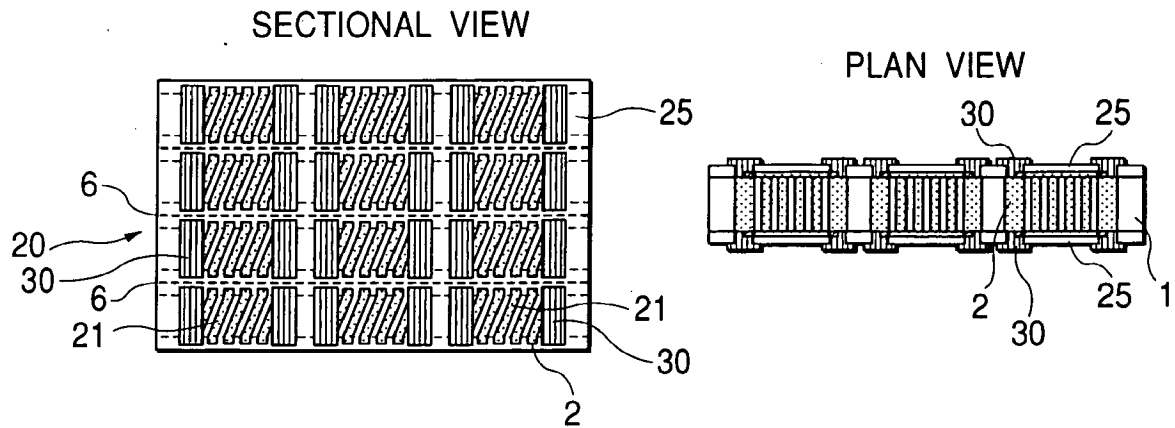
**FIG. 6B**

FORMATION OF PROTECTIVE LAYER



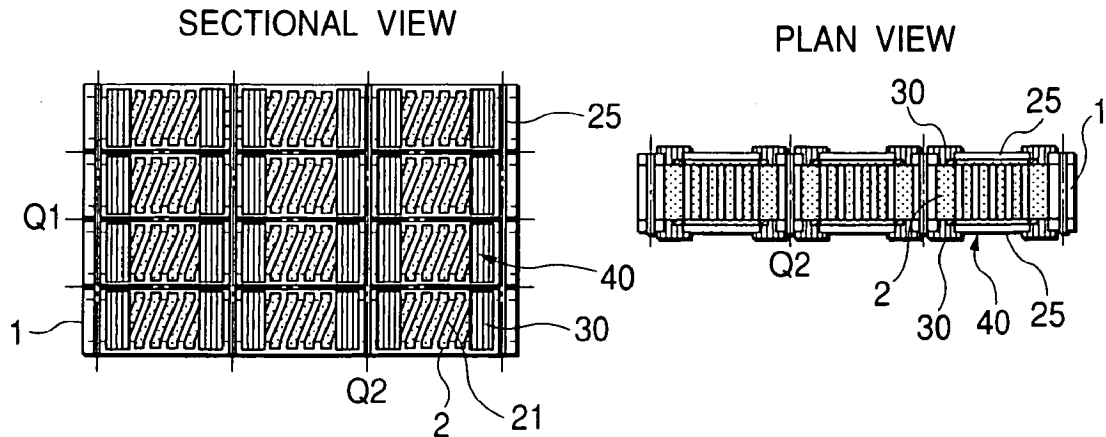
**FIG. 6C**

FORMATION OF TERMINAL ELECTRODE



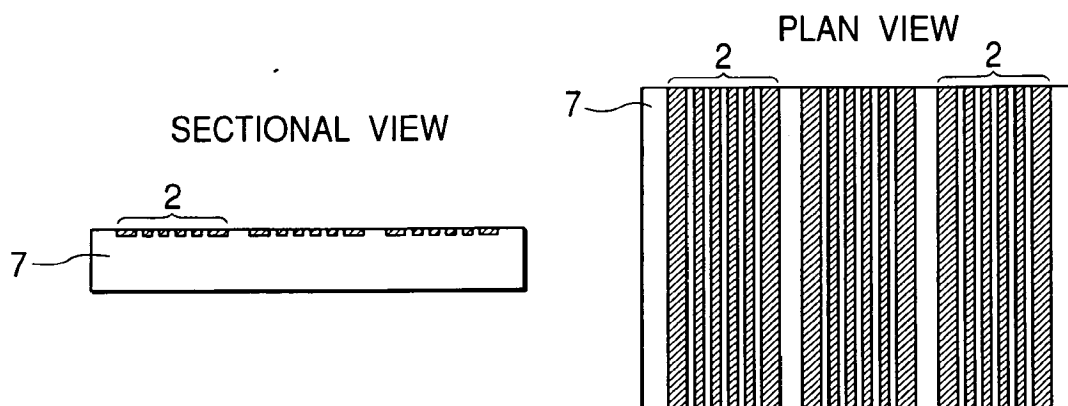
**FIG. 6D**

SEPARATION INTO CHIPS



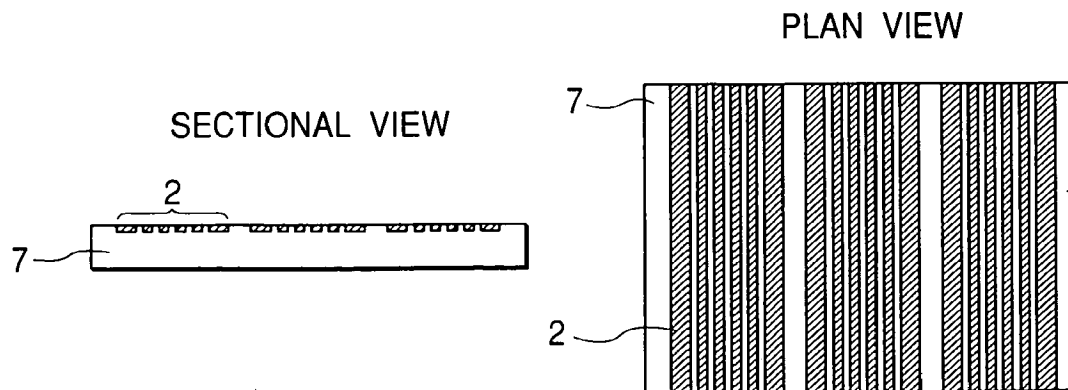
**FIG. 7A**

PRODUCTION OF BAND-SHAPED CONDUCTOR



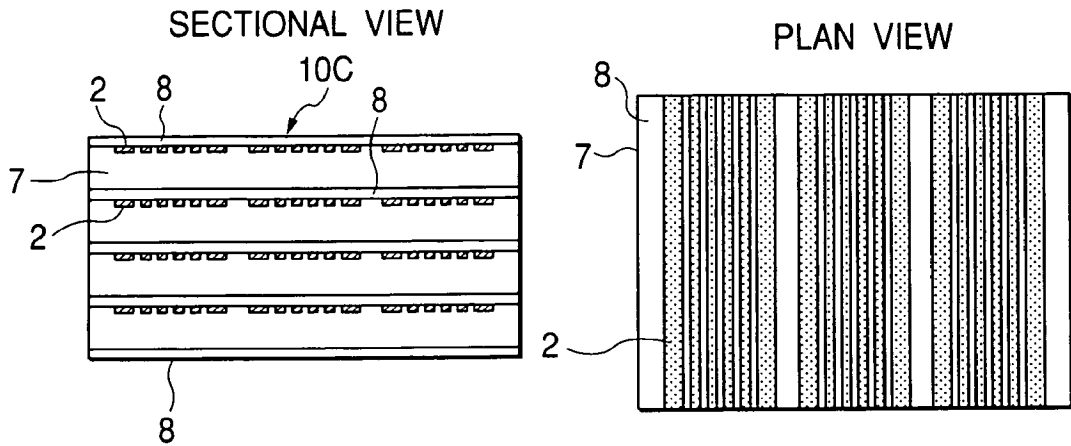
**FIG. 7B**

ADJUSTMENT OF BOARD THICKNESS



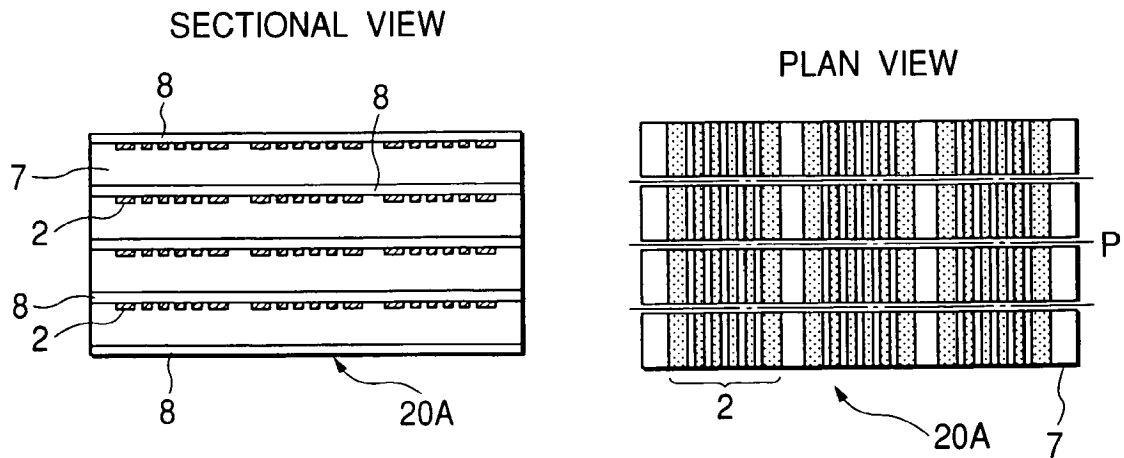
**FIG. 7C**

LAMINATION



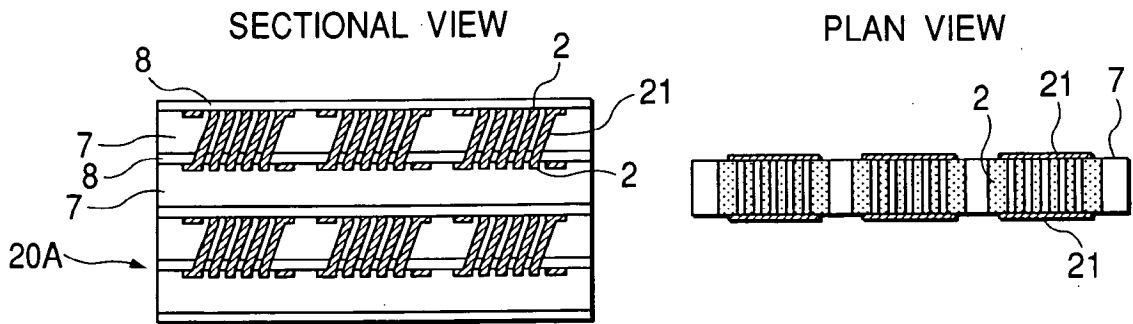
**FIG. 7D**

SLICING



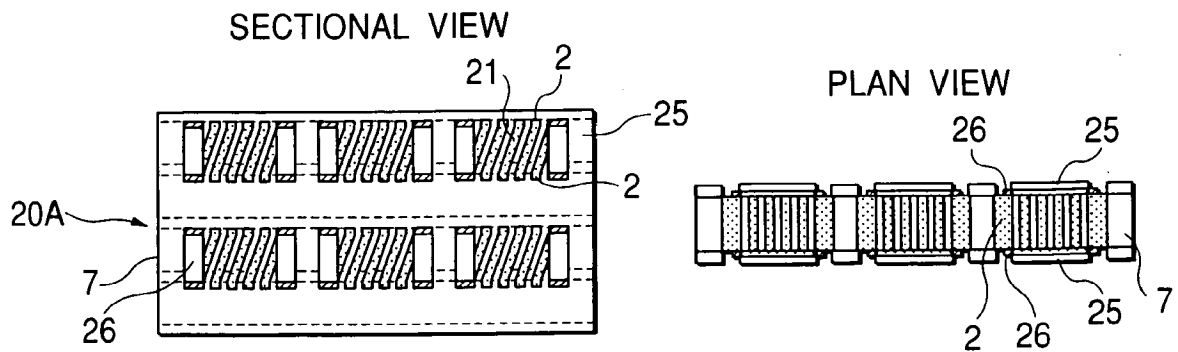
**FIG. 8A**

FORMATION OF BRIDGING CONDUCTOR



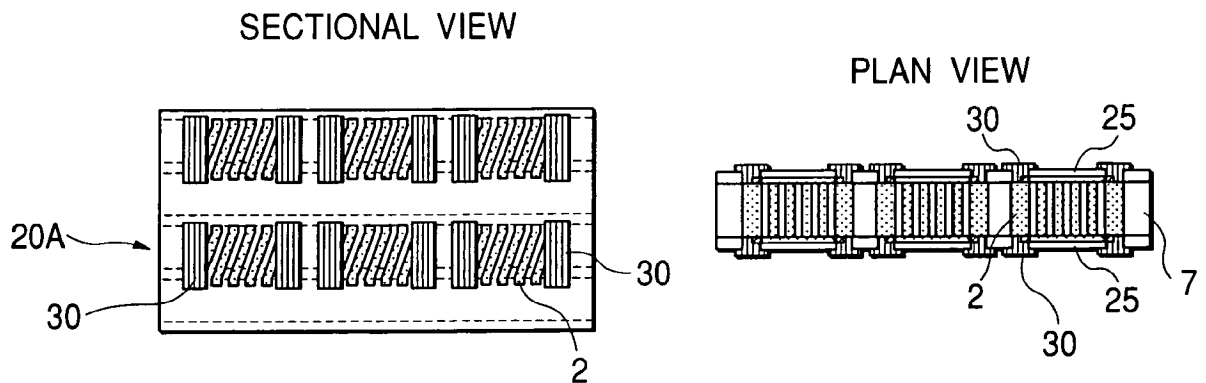
**FIG. 8B**

FORMATION OF PROTECTIVE LAYER



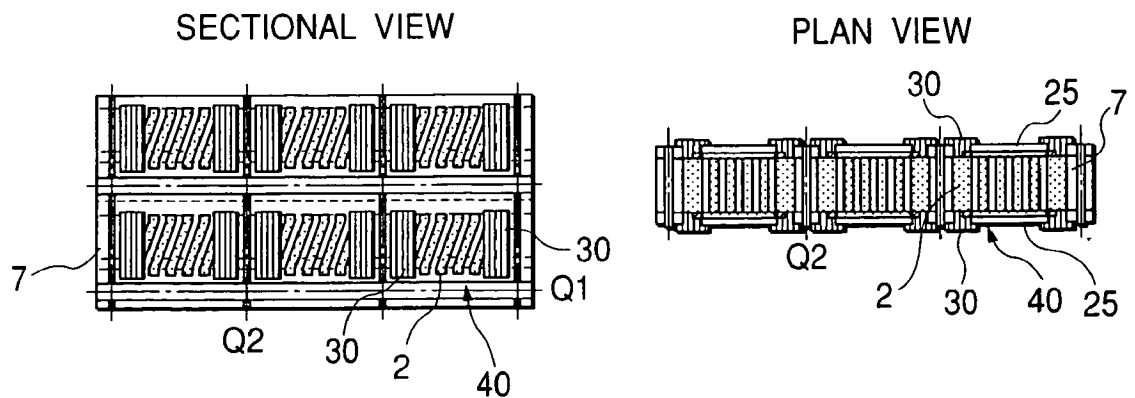
**FIG. 8C**

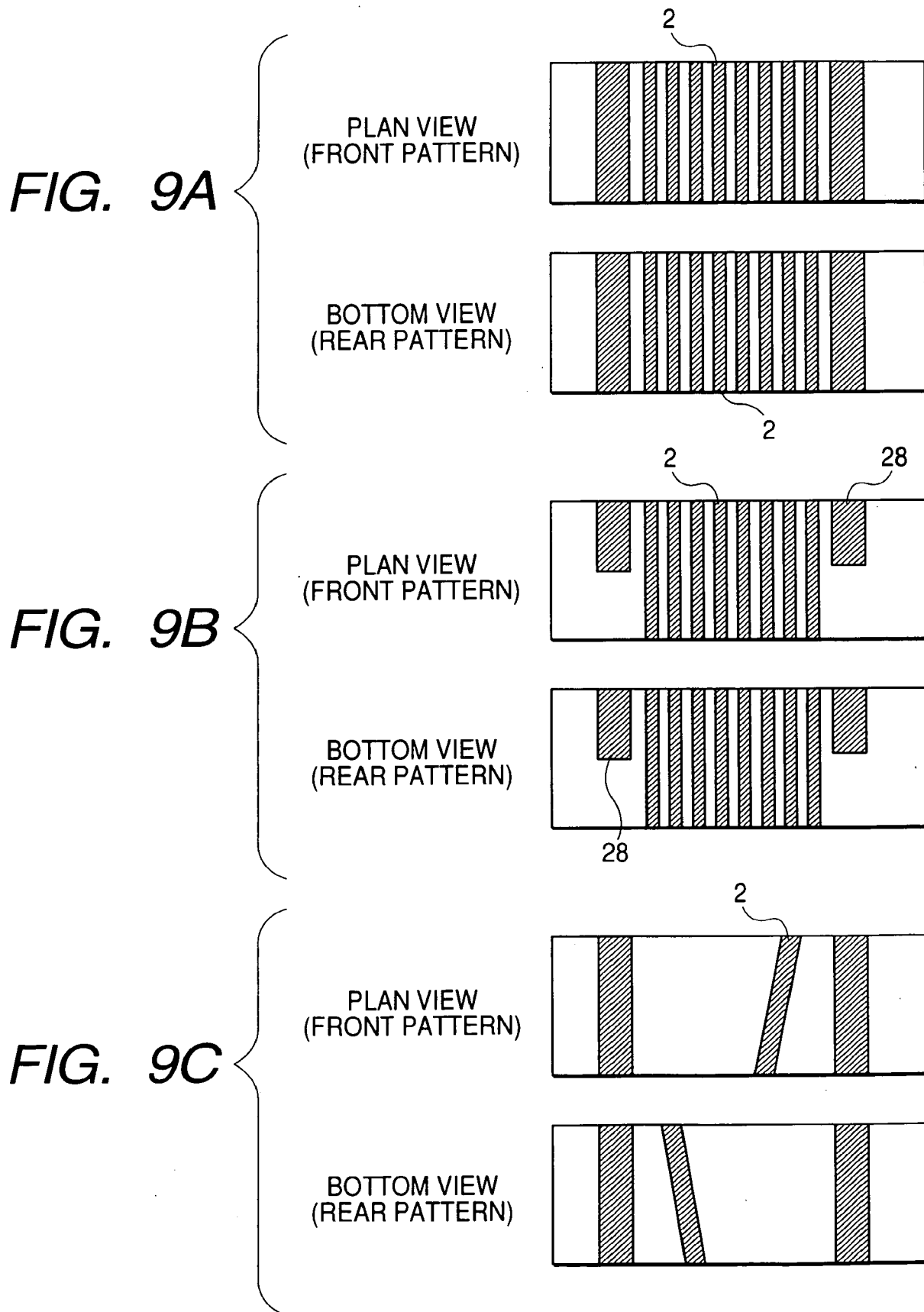
FORMATION OF TERMINAL ELECTRODE



**FIG. 8D**

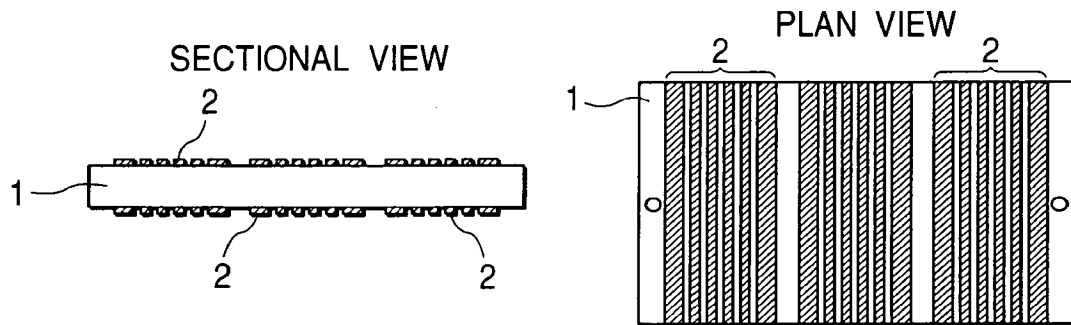
SEPARATION INTO CHIPS





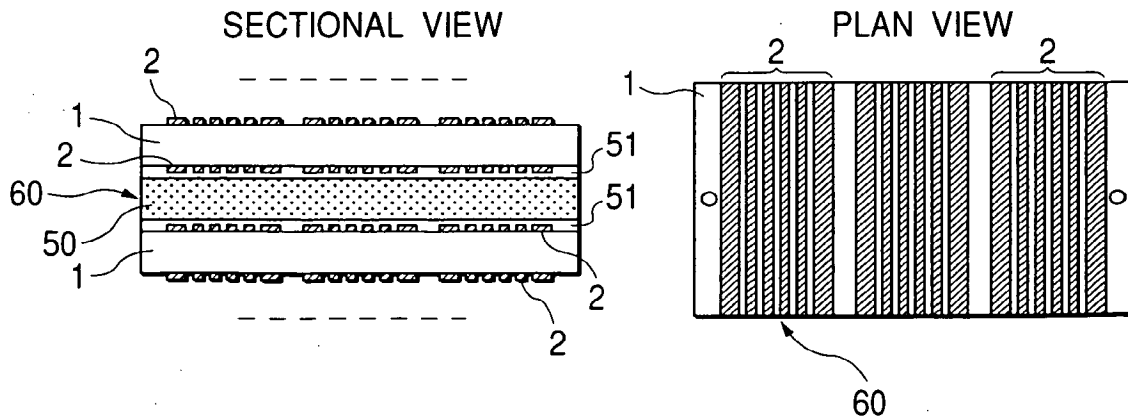
**FIG. 10A**

PRODUCTION OF BAND-SHAPED CONDUCTOR



**FIG. 10B**

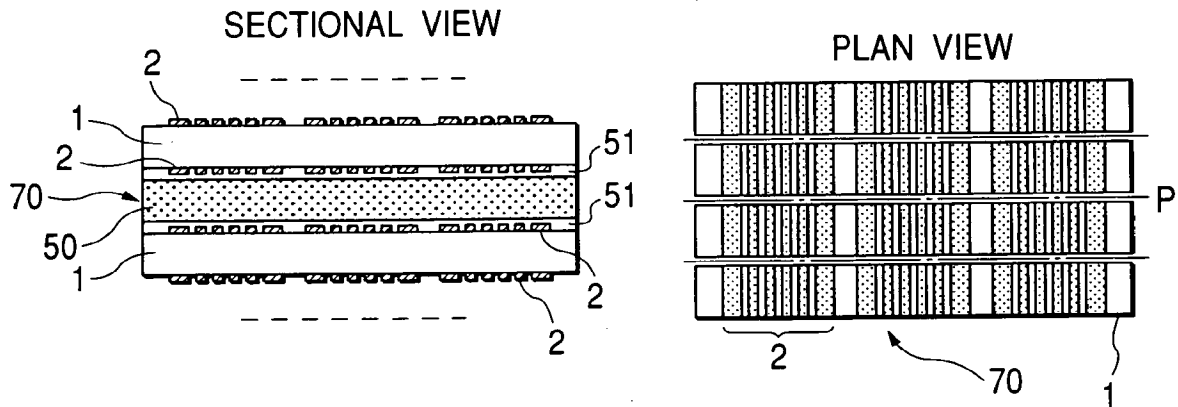
LAMINATION





**FIG. 10C**

SLICING



**FIG. 10D**

FORMATION OF BRIDGING CONDUCTOR

